

Title (en)  
Method of depositing a MCrAlY bond coating

Title (de)  
Verfahren zur MCrAlY-Haftungsbeschichtung

Title (fr)  
Procédé pour la déposition d'une couche de liaison à base de MCrAlY

Publication  
**EP 1260608 A1 20021127 (EN)**

Application  
**EP 01112646 A 20010525**

Priority  
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Abstract (en)  
It is disclosed a method of depositing a bond MCrAlY-coating to a surface of an article for increasing the roughness for enhanced TBC adhesion. First, an inner layer on top of the surface of the article consisting of gamma / gamma '-MCrAlY is deposited using powder in the size range from 5 to 65 mu m. Second, an outer bond coating layer on top of the inner layer consisting of beta -NiAl or gamma / beta -MCrAlY or gamma / gamma '-MCrAlY is deposited using powder in the size range from 30 to 125 mu m.

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Citation (search report)

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